# E·XFL

# Intel - EPM7128SLC84-7N Datasheet



Welcome to E-XFL.COM

#### Understanding <u>Embedded - CPLDs (Complex</u> <u>Programmable Logic Devices)</u>

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixedfunction ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

#### Applications of Embedded - CPLDs

#### Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	68
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	84-LCC (J-Lead)
Supplier Device Package	84-PLCC (29.31x29.31)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128slc84-7n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

The MAX 7000E devices—including the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices—have several enhanced features: additional global clocking, additional output enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

In-system programmable MAX 7000 devices—called MAX 7000S devices—include the EPM7032S, EPM7064S, EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices. MAX 7000S devices have the enhanced features of MAX 7000E devices as well as JTAG BST circuitry in devices with 128 or more macrocells, ISP, and an open-drain output option. See Table 4.

Feature	EPM7032 EPM7064 EPM7096	All MAX 7000E Devices	All MAX 7000S Devices
ISP via JTAG interface			$\checkmark$
JTAG BST circuitry			✓(1)
Open-drain output option			$\checkmark$
Fast input registers		~	$\checkmark$
Six global output enables		~	$\checkmark$
Two global clocks		~	$\checkmark$
Slew-rate control		~	$\checkmark$
MultiVolt interface (2)	$\checkmark$	~	$\checkmark$
Programmable register	$\checkmark$	~	$\checkmark$
Parallel expanders	$\checkmark$	~	$\checkmark$
Shared expanders	$\checkmark$	~	$\checkmark$
Power-saving mode	$\checkmark$	~	$\checkmark$
Security bit	$\checkmark$	~	$\checkmark$
PCI-compliant devices available	$\checkmark$	$\checkmark$	$\checkmark$

Notes:

(1) Available only in EPM7128S, EPM7160S, EPM7192S, and EPM7256S devices only.

(2) The MultiVolt I/O interface is not available in 44-pin packages.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-tooutput performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

# **Expander Product Terms**

Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

# **Programming Sequence**

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- 1. *Enter ISP*. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase.* Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- 4. *Program*. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- 5. *Verify.* Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. *Exit ISP*. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

## **Programming Times**

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

### Programming a Single MAX 7000S Device

The time required to program a single MAX 7000S device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$
where:  $t_{PROG}$  = Programming time  
 $t_{PPULSE}$  = Sum of the fixed times to erase, program, and  
verify the EEPROM cells  
 $Cycle_{PTCK}$  = Number of TCK cycles to program a device  
 $f_{TCK}$  = TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000S device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$
where:  $t_{VER}$  = Verify time  
 $t_{VPULSE}$  = Sum of the fixed times to verify the EEPROM cells  
 $Cycle_{VTCK}$  = Number of TCK cycles to verify a device

The programming times described in Tables 6 through 8 are associated

Device	Progra	mming	Stand-Alone Verification				
	t <sub>PPULSE</sub> (s)	Cycle <sub>PTCK</sub>	t <sub>VPULSE</sub> (s)	Cycle <sub>VTCK</sub>			
EPM7032S	4.02	342,000	0.03	200,000			
EPM7064S	4.50	504,000	0.03	308,000			
EPM7128S	5.11	832,000	0.03	528,000			
EPM7160S	5.35	1,001,000	0.03	640,000			
EPM7192S	5.71	1,192,000	0.03	764,000			
EPM7256S	6.43	1,603,000	0.03	1,024,000			

with the worst-case method using the enhanced ISP algorithm.

Tables 7 and 8 show the in-system programming and stand alone verification times for several common test clock frequencies.

Device				1	тск				Units			
	10 MHz	0 MHz 5 MHz 2 MHz 1 MHz 500 kHz 200 kHz 100 kHz 50 kHz										
EPM7032S	4.06	4.09	4.19	4.36	4.71	5.73	7.44	10.86	s			
EPM7064S	4.55	4.60	4.76	5.01	5.51	7.02	9.54	14.58	S			
EPM7128S	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	s			
EPM7160S	5.45	5.55	5.85	6.35	7.35	10.35	15.36	25.37	S			
EPM7192S	5.83	5.95	6.30	6.90	8.09	11.67	17.63	29.55	S			
EPM7256S	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S			

Table 8. MAX 7000S Stand-Alone Verification Times for Different Test Clock Frequencies

	1								1
Device				f	тск				Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032S	0.05	0.07	0.13	0.23	0.43	1.03	2.03	4.03	S
EPM7064S	0.06	0.09	0.18	0.34	0.64	1.57	3.11	6.19	S
EPM7128S	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	S
EPM7160S	0.09	0.16	0.35	0.67	1.31	3.23	6.43	12.83	S
EPM7192S	0.11	0.18	0.41	0.79	1.56	3.85	7.67	15.31	S
EPM7256S	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	S

devices.

Figure 9 shows the timing requirements for the JTAG signals.

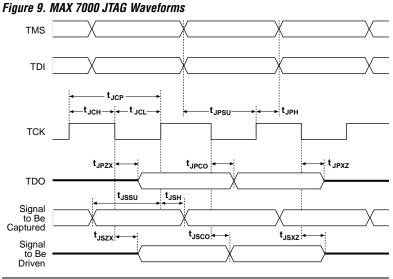


Table 12 shows the JTAG timing parameters and values for MAX 7000S

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Мах	Unit
t <sub>JCP</sub>	TCK clock period	100		ns
t <sub>JCH</sub>	TCK clock high time	50		ns
t <sub>JCL</sub>	TCK clock low time	50		ns
t <sub>JPSU</sub>	JTAG port setup time	20		ns
t <sub>JPH</sub>	JTAG port hold time	45		ns
t <sub>JPCO</sub>	JTAG port clock to output		25	ns
t <sub>JPZX</sub>	JTAG port high impedance to valid output		25	ns
t <sub>JPXZ</sub>	JTAG port valid output to high impedance		25	ns
t <sub>JSSU</sub>	Capture register setup time	20		ns
t <sub>JSH</sub>	Capture register hold time	45		ns
t <sub>JSCO</sub>	Update register clock to output		25	ns
t <sub>JSZX</sub>	Update register high impedance to valid output		25	ns
t <sub>JSXZ</sub>	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (IEEE 1149.1 (JTAG) *Boundary-Scan Testing in Altera Devices*).

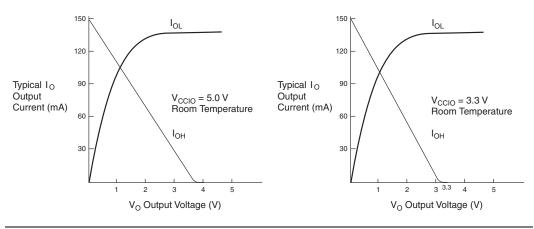
#### MAX 7000 Programmable Logic Device Family Data Sheet

#### Notes to tables:

- (1) See the Operating Requirements for Altera Devices Data Sheet.
- (2) Minimum DC input voltage on I/O pins is -0.5 V and on 4 dedicated input pins is -0.3 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to 7.0 V for input currents less than 100 mA and periods shorter than 20 ns.
- (3) Numbers in parentheses are for industrial-temperature-range devices.
- (4) V<sub>CC</sub> must rise monotonically.
- (5) The POR time for all 7000S devices does not exceed 300 μs. The sufficient V<sub>CCINT</sub> voltage level for POR is 4.5 V. The device is fully initialized within the POR time after V<sub>CCINT</sub> reaches the sufficient POR voltage level.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) The V<sub>CCISP</sub> parameter applies only to MAX 7000S devices.
- (8) During in-system programming, the minimum DC input voltage is -0.3 V.
- (9) These values are specified under the MAX 7000 recommended operating conditions in Table 14 on page 26.
- (10) The parameter is measured with 50% of the outputs each sourcing the specified current. The I<sub>OH</sub> parameter refers to high-level TTL or CMOS output current.
- (11) The parameter is measured with 50% of the outputs each sinking the specified current. The I<sub>OL</sub> parameter refers to low-level TTL, PCI, or CMOS output current.
- (12) When the JTAG interface is enabled in MAX 7000S devices, the input leakage current on the JTAG pins is typically -60 μA.
- (13) Capacitance is measured at 25° C and is sample-tested only. The OE1 pin has a maximum capacitance of 20 pF.

Figure 11 shows the typical output drive characteristics of MAX 7000 devices.

#### Figure 11. Output Drive Characteristics of 5.0-V MAX 7000 Devices



**Timing Model** 

MAX 7000 device timing can be analyzed with the Altera software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 12. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. The Altera software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for a device-wide performance evaluation.

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC  $\,$ operating conditions.

Symbol	Parameter	Conditions	-6 Spee	d Grade	-7 Spee	d Grade	Unit
			Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t <sub>SU</sub>	Global clock setup time		5.0		6.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.5		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t <sub>CH</sub>	Global clock high time		2.5		3.0		ns
t <sub>CL</sub>	Global clock low time		2.5		3.0		ns
t <sub>ASU</sub>	Array clock setup time		2.5		3.0		ns
t <sub>AH</sub>	Array clock hold time		2.0		2.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.6		8.0	ns
<sup>f</sup> сnт	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			6.6		8.0	ns
facnt	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	200		166.7		MHz

Table 2	21. MAX 7000 & MAX 7000E Ext	ernal Timing Parame	eters Note	(1)				
Symbol	Parameter	Conditions		Speed (	Grade		Unit	
			MAX 700	0E (-10P)		00 (-10) Doe (-10)		
			Min	Max	Min	Max		
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		10.0		10.0	ns	
t <sub>SU</sub>	Global clock setup time		7.0		8.0		ns	
t <sub>H</sub>	Global clock hold time		0.0		0.0		ns	
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		3.0		ns	
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.5		0.5		ns	
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		5.0		5	ns	
t <sub>CH</sub>	Global clock high time		4.0		4.0		ns	
t <sub>CL</sub>	Global clock low time		4.0		4.0		ns	
t <sub>ASU</sub>	Array clock setup time		2.0		3.0		ns	
t <sub>AH</sub>	Array clock hold time		3.0		3.0		ns	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		10.0		10.0	ns	
t <sub>ACH</sub>	Array clock high time		4.0		4.0		ns	
t <sub>ACL</sub>	Array clock low time		4.0		4.0		ns	
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	4.0		4.0		ns	
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns	
t <sub>CNT</sub>	Minimum global clock period			10.0		10.0	ns	
f <sub>CNT</sub>	Maximum internal global clock frequency	(5)	100.0		100.0		MHz	
t <sub>ACNT</sub>	Minimum array clock period			10.0		10.0	ns	
f <sub>acnt</sub>	Maximum internal array clock frequency	(5)	100.0		100.0		MHz	
f <sub>MAX</sub>	Maximum clock frequency	(6)	125.0		125.0		MHz	

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	0E (-10P)		00 (-10) Doe (-10)	
			Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.5		1.0	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.5		1.0	ns
t <sub>FIN</sub>	Fast input delay	(2)		1.0		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			5.0		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.8		0.8	ns
t <sub>LAD</sub>	Logic array delay			5.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			5.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay	(2)		2.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t <sub>OD2</sub>	Output buffer and pad delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		2.0		2.5	ns
t <sub>OD3</sub>	Output buffer and pad delay Slow slew rate = on $V_{CCIO} = 5.0 V \text{ or } 3.3 V$	C1 = 35 pF (2)		5.5		6.0	ns
t <sub>ZX1</sub>	Output buffer enable delay Slow slew rate = off V <sub>CCIO</sub> = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3 V$	C1 = 35 pF (7)		5.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay Slow slew rate = on V <sub>CCIO</sub> = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t <sub>XZ</sub>	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t <sub>SU</sub>	Register setup time		2.0		3.0		ns
t <sub>H</sub>	Register hold time		3.0		3.0		ns
t <sub>FSU</sub>	Register setup time of fast input	(2)	3.0		3.0		ns
t <sub>FH</sub>	Register hold time of fast input	(2)	0.5		0.5		ns
t <sub>RD</sub>	Register delay			2.0		1.0	ns
t <sub>COMB</sub>	Combinatorial delay			2.0		1.0	ns
t <sub>IC</sub>	Array clock delay			5.0		5.0	ns
t <sub>EN</sub>	Register enable time			5.0		5.0	ns
t <sub>GLOB</sub>	Global control delay			1.0		1.0	ns
t <sub>PRE</sub>	Register preset time			3.0		3.0	ns
t <sub>CLR</sub>	Register clear time			3.0		3.0	ns
t <sub>PIA</sub>	PIA delay			1.0		1.0	ns
t <sub>LPA</sub>	Low-power adder	(8)		11.0		11.0	ns

	5. MAX 7000 & MAX 7000E	-	aramete		lote (1)				
Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	15	-1	5T	-2	20	
			Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>SU</sub>	Global clock setup time		11.0		11.0		12.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	(2)	3.0		-		5.0		ns
t <sub>FH</sub>	Global clock hold time of fast input	(2)	0.0		-		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		8.0		8.0		12.0	ns
t <sub>CH</sub>	Global clock high time		5.0		6.0		6.0		ns
t <sub>CL</sub>	Global clock low time		5.0		6.0		6.0		ns
t <sub>ASU</sub>	Array clock setup time		4.0		4.0		5.0		ns
t <sub>AH</sub>	Array clock hold time		4.0		4.0		5.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		15.0		15.0		20.0	ns
t <sub>ACH</sub>	Array clock high time		6.0		6.5		8.0		ns
t <sub>ACL</sub>	Array clock low time		6.0		6.5		8.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(3)	6.0		6.5		8.0		ns
t <sub>odh</sub>	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			13.0		13.0		16.0	ns
fcnt	Maximum internal global clock frequency	(5)	76.9		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13.0		13.0		16.0	ns
facnt	Maximum internal array clock frequency	(5)	76.9		76.9		62.5		MHz
f <sub>MAX</sub>	Maximum clock frequency	(6)	100		83.3		83.3		MHz

#### Notes to tables:

- (1) These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This parameter applies to MAX 7000E devices only.
- (3) This minimum pulse width for preset and clear applies for both global clear and array controls. The t<sub>LPA</sub> parameter must be added to this minimum width if the clear or reset signal incorporates the t<sub>LAD</sub> parameter into the signal path.
- (4) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (5) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (6) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (7) Operating conditions:  $V_{CCIO} = 3.3 \text{ V} \pm 10\%$  for commercial and industrial use.
- (8) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{EN}$ ,  $t_{SEXP}$ ,  $t_{ACL}$ , and  $t_{CPPW}$  parameters for macrocells running in the low-power mode.

#### Tables 27 and 28 show the EPM7032S AC operating conditions.

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	-5		6	-7		-1	0	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns
t <sub>SU</sub>	Global clock setup time		2.9		4.0		5.0		7.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		2.5		2.5		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.0		0.0		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.2		3.5		4.3		5.0	ns
t <sub>CH</sub>	Global clock high time		2.0		2.5		3.0		4.0		ns
t <sub>CL</sub>	Global clock low time		2.0		2.5		3.0		4.0		ns
t <sub>ASU</sub>	Array clock setup time		0.7		0.9		1.1		2.0		ns
t <sub>AH</sub>	Array clock hold time		1.8		2.1		2.7		3.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.6		8.2		10.0	ns
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t <sub>odh</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		7.0		8.6		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		142.9		116.3		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.0		8.6		10.0	ns

Table 2	9. EPM7064S External Timi	ing Parameters	(Part 2	2 of 2)	No	te (1)					
Symbol	Parameter	Conditions	Speed Grade								
			-	5	-	6	-	7	-1	0	
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns
t <sub>ACH</sub>	Array clock high time		2.5		2.5		3.0		4.0		ns
t <sub>ACL</sub>	Array clock low time		2.5		2.5		3.0		4.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			5.7		7.1		8.0		10.0	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.7		7.1		8.0		10.0	ns
f <sub>acnt</sub>	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz

# Г

Table 30. EPM7064S Internal Timing Parameters (Part 1 of 2) Note (1)

Symbol	Parameter	Conditions	Speed Grade								
			-5		-6		-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>IN</sub>	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t <sub>IO</sub>	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t <sub>FIN</sub>	Fast input delay			2.2		2.6		1.0		1.0	ns
t <sub>SEXP</sub>	Shared expander delay			3.1		3.8		4.0		5.0	ns
t <sub>PEXP</sub>	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t <sub>LAD</sub>	Logic array delay			2.6		3.2		3.0		5.0	ns
t <sub>LAC</sub>	Logic control array delay			2.5		3.2		3.0		5.0	ns
t <sub>IOE</sub>	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t <sub>OD1</sub>	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t <sub>OD2</sub>	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t <sub>OD3</sub>	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t <sub>ZX1</sub>	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t <sub>ZX2</sub>	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t <sub>ZX3</sub>	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t <sub>XZ</sub>	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t <sub>SU</sub>	Register setup time		0.8		1.0		3.0		2.0		ns
t <sub>H</sub>	Register hold time		1.7		2.0		2.0		3.0		ns

Symbol	Parameter	Conditions	Speed Grade								
			-6		-7		-10		-15		
			Min	Max	Min	Max	Min	Max	Min	Max	
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		6.0		7.5		10.0		15.0	ns
t <sub>SU</sub>	Global clock setup time		3.4		6.0		7.0		11.0		ns
t <sub>H</sub>	Global clock hold time		0.0		0.0		0.0		0.0		ns
t <sub>FSU</sub>	Global clock setup time of fast input		2.5		3.0		3.0		3.0		ns
t <sub>FH</sub>	Global clock hold time of fast input		0.0		0.5		0.5		0.0		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		4.0		4.5		5.0		8.0	ns
t <sub>CH</sub>	Global clock high time		3.0		3.0		4.0		5.0		ns
t <sub>CL</sub>	Global clock low time		3.0		3.0		4.0		5.0		ns
t <sub>ASU</sub>	Array clock setup time		0.9		3.0		2.0		4.0		ns
t <sub>AH</sub>	Array clock hold time		1.8		2.0		5.0		4.0		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		6.5		7.5		10.0		15.0	ns
t <sub>ACH</sub>	Array clock high time		3.0		3.0		4.0		6.0		ns
t <sub>ACL</sub>	Array clock low time		3.0		3.0		4.0		6.0		ns
t <sub>CPPW</sub>	Minimum pulse width for clear and preset	(2)	3.0		3.0		4.0		6.0		ns
t <sub>ODH</sub>	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns
t <sub>CNT</sub>	Minimum global clock period			6.8		8.0		10.0		13.0	ns
fcnt	Maximum internal global clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
t <sub>acnt</sub>	Minimum array clock period			6.8		8.0		10.0		13.0	ns
f <sub>acnt</sub>	Maximum internal array clock frequency	(4)	147.1		125.0		100.0		76.9		MHz
f <sub>MAX</sub>	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

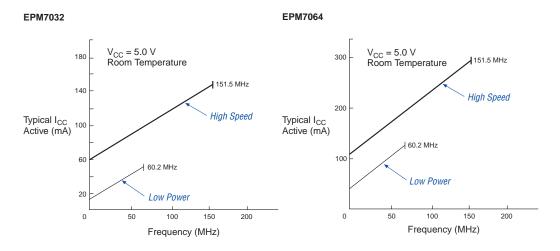
Tables 31 and 32 show the EPM7128S AC operating conditions.

٦

Г

Figure 14 shows typical supply current versus frequency for MAX 7000 devices.





EPM7096

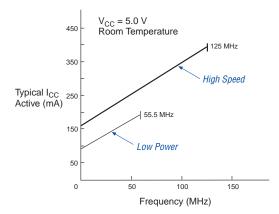
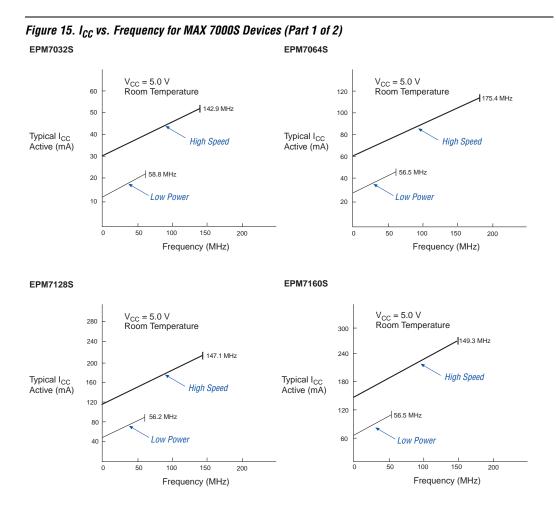
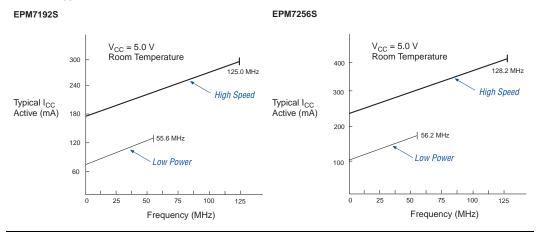


Figure 15 shows typical supply current versus frequency for MAX 7000S devices.





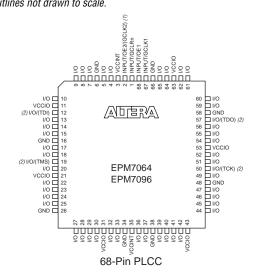
## Figure 15. I<sub>CC</sub> vs. Frequency for MAX 7000S Devices (Part 2 of 2)

# Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

#### Figure 17. 68-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.

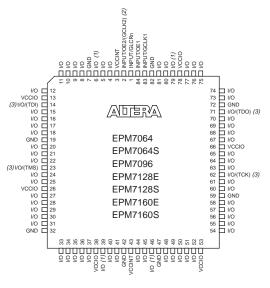


#### Notes:

- The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

#### Figure 18. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



84-Pin PLCC

Notes:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096, EPM7160E, and EPM7160S devices.
- (2) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (3) JTAG ports are available in MAX 7000S devices only.

